



PCN Number:	20150625002		PCN Date:	06/30/2015	
Title:	Qualification of JCAP China as an alternate Bump, Assembly, and Test Site for select WCSP Devices				
Customer Contact:		PCN Manager	Dept:	Quality Services	
Proposed 1st Ship Date:	09/30/2015	Estimated Sample Availability:	Date provided upon request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input checked="" type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
PCN Details					
Description of Change:					
<p>Texas Instruments is pleased to announce the qualification of JCAP China as an alternate Bump, Assembly, and Test site for the devices shown below. The material set will be the same between the 2 sites.</p> <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>					
Reason for Change:					
Continuity of Supply					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
None					

Changes to product identification resulting from this PCN:							
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City				
TI Clark	QAB	PHL	Angeles City, Pampanga				
JCAP	JCP	CHN	Jiangsu				
<p>Sample product shipping label (not actual product label)</p> <div style="display: flex; justify-content: space-between;"> <div style="width: 30%;">  <p>MADE IN: Malaysia 2DC: 20:</p> <table border="1" style="font-size: small;"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39 LBL: 5A (L)T0:1750</p> </div> <div style="width: 20%; text-align: center;">  </div> <div style="width: 40%;"> <p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CS0: SHE (21L) CCO:USA (22L) AS0: MLA (23L) ACO: MYS</p> </div> </div>				MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04
MSL 2 /260C/1 YEAR	SEAL DT						
MSL 1 /235C/UNLIM	03/29/04						
Topside Device marking:							
Assembly site code for QAB= I							
Assembly site code for JCP= P							

Product Affected

TPS65132A0YFFR	TPS65132AYFFR	TPS65132B0YFFR	TPS65132BYFFR
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TI Information
Selective Disclosure

Qualification Report

TPS65132BYFFR, TPS65132B0YFFR, TPS65132AYFFR & TPS65132A0YFFR JCAP Multi-Source 2nd Site
Approve Date 27-May-2015

Product Attributes

Attributes	Qual Device: TPS65132B0YFF	Qual Device: TPS65132AYFF	QBS Package Reference: DRV2604YZF	QBS Package Reference: CD3230A0YFF
Assembly Site	JCAP	JCAP	JCAP	JCAP
Package Family	WCSP	WCSP	WCSP	WCSP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	RFAB	RFAB	RFAB
Wafer Process	LBC7	LBC7	LBC8LV	LBC7

- QBS: Qual By Similarity
- Qual Devices qualified at LEVEL1-260C: TPS65132A0YFF, TPS65132AYFF
- Qual Devices qualified at LEVEL1-260CG: TPS65132B0YFF, TPS65132BYFFR

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS65132B0YFF	Qual Device: TPS65132AYFF	QBS Package Reference: DRV2604YZF	QBS Package Reference: CD3230A0YFF
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass		
HAST	Biased HAST, 130C/85%RH	96 Hours			3/231/0	1/77/0
HBM	ESD - HBM	4000 V			3/9/0	
CDM	ESD - CDM	1500 V			3/9/0	
HTOL	Life Test, 125C	1000 Hours				1/80/0
HTOL	Life Test, 140C	480 Hours			3/231/0	
HTOL	Life Test, 150C	300 Hours				
HTSL	High Temp. Storage Bake, 170C	420 Hours			3/135/0	3/231/0
LU	Latch-up	(per JESD78)			3/18/0	
PD	Physical Dimensions	--			3/60/0	3/15/0
SBS	Bump-shear	Solder Bumps			3/135/0	3/150/0
TC	Temperature Cycle, -55/125C	700 Cycles			3/231/0	
UHAST	Unbiased HAST 130C/85%RH	96 Hours				3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com